



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
<i>* : Required Field</i>			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2017-02-02
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Rossana Bonaccorso	Representative Title	ADG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
EMIF06-1005MX12Y	EC88*EMI6TG Y	A	SA1A	2017-02-02
	Amount	UoM	Unit type	ST ECOPACK Grade
	8.61	mg	Each	ECOPACK® 2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
CHP	0.3-1.35-0.8	12	No lead	
Comment	Package: DFN.30.135.08-050-12L-E			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015

Query		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
5 - Product(s) is obsolete, no information is available		false
6 - Product(s) is unknown, no information is available		false
Exemption Id.	Description	

QueryList : REACH-12th January 2017

Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	EC88*EMI6T6Y					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.112	mg	supplier	die	Silicon (Si)	7440-21-3		0.108	mg	964286	12544
				supplier	metallization	Aluminium (Al)	7429-90-5		0.002	mg	17856	232
				supplier	Passivation	Silicon Oxide	7631-86-9		0.001	mg	8929	116
				supplier	back side metallization	Nickel (Ni)	7440-02-0		0.001	mg	8929	116
Leadframe	Copper & its alloys	3.013	mg	supplier	Alloy	Copper(Cu)	7440-50-8		2.910	mg	965815	337979
				supplier	Alloy	Iron(Fe)	7439-89-6		0.068	mg	22569	7898
				supplier	Alloy	Phosphorus (P)	7723-14-0		0.001	mg	331	116
				supplier	Alloy	Zinc (Zn)	7440-66-6		0.004	mg	1328	466
				supplier	Alloy	Silver(Ag)	7440-22-4		0.030	mg	9957	3484
Die attach	Other Organic Materials	0.031	mg	supplier	Adhesive	Silver (Ag)	7440-22-4		0.027	mg	870968	3136
				supplier	Adhesive	Carbocyclic acrylate	Proprietary		0.003	mg	96774	348
				supplier	Adhesive	2-Propenoic acid, 2-methyl-, 2-[[2,3,3a,4,7,7a]]	68586-19-6		0.001	mg	32258	116
Bonding wire	Other inorganic materials	0.029	mg	supplier	Bonding wire	Copper (Cu)	7440-50-8		0.029	mg	1000000	3368
Encapsulation	Other Organic Materials	5.293	mg	supplier	Mold compound	Silica Fused (Si)	60676-86-0		4.959	mg	936898	575958
				supplier	Mold compound	Epoxy Resin	25068-38-6		0.159	mg	30040	18467
				supplier	Mold compound	Phenol Resin	29690-82-2		0.159	mg	30040	18467
				supplier	Mold compound	Carbon Black (C)	1333-86-4		0.016	mg	3022	1858
Finishing	Other inorganic materials	0.132	mg	supplier	Connection coating	Tin(Sn)	7440-31-5		0.132	mg	1000000	15331